

# NOT RECOMMENDED FOR NEW DESIGN CONTACT US



DMC3021LK4

#### COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

#### **Product Summary**

Device	V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>C</sub> = +25°C
01	30V	21mΩ @ V <sub>GS</sub> = 10V	14A
Q1	307	32mΩ @ V <sub>GS</sub> = 4.5V	14A
02	2017	$39m\Omega$ @ $V_{GS}$ = -10 $V$	-14A
Q2	-30V	53mΩ @ V <sub>GS</sub> = -4.5V	-14A

#### **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Power Management Functions
- DC-DC Converters
- Backlighting

### **Features and Benefits**

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

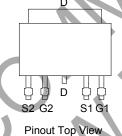
#### **Mechanical Data**

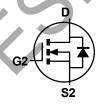
- Case: TO252-4
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 €3
- Weight: 0.027 grams (approximate)

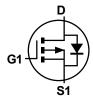












Top View

**Bottom View** 

N-Channel MOSFET

P-Channel MOSFET

#### Ordering Information (Note 4)

Part Number	Case	Packaging
DMC3021LK4-13	TO252-4	2500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

#### **Marking Information**



OH = Manufacturer's Marking
C3021L = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 11 = 2011)
WW = Week (01 - 53)



### Maximum Ratings N-CHANNEL – Q1 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	30	V	
Gate-Source Voltage	$V_{GSS}$	±20	V		
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	9.4 7.5	Α
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	$T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$	I <sub>D</sub>	14 14	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	6)	I <sub>DM</sub>	70	Α	
Avalanche Current, (Notes 7) L = 0.1mH	I <sub>AS</sub>	16	Α		
Avalanche Energy, (Notes 7) L = 0.1mH	E <sub>AS</sub>	13	mJ		

### Maximum Ratings P-CHANNEL - Q2 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage			$V_{DSS}$	-30	V
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l <sub>D</sub>	-6.8 -5.3	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	$T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$	I <sub>D</sub>	-14 -14	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-50	Α
Avalanche Current, (Notes 7) L = 0.1mH		114	I <sub>AS</sub>	-16	Α
Avalanche Energy, (Notes 7) L = 0.1mH			E <sub>AS</sub>	13	mJ

## Thermal Characteristics @T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	<u> </u>	Symbol	Value	Units
Total Power Dissipation (Note 6)	$T_A = +25$ °C		2.7	· w
Total Fower Dissipation (Note 6)	$T_A = +70^{\circ}C$	Р	1.7	
Total Davis Dissination (Nata C)	T <sub>C</sub> = +25°C	$P_D$	22	
Total Power Dissipation (Note 6)	T <sub>C</sub> = +70°C		14	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	46	°C/W
Thermal Resistance, Junction to Case (Note 6)	Steady state	$R_{\theta}$ JC	5.5	C/VV
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

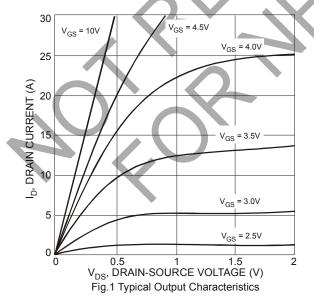
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
   Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate
   I<sub>AS</sub> and E<sub>AS</sub> rating are based on low frequency and duty cycles to keep T<sub>J</sub> = 25°C
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.

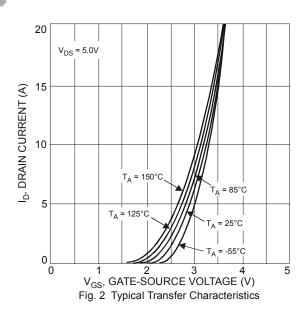


## Electrical Characteristics N-CHANNEL – Q1 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

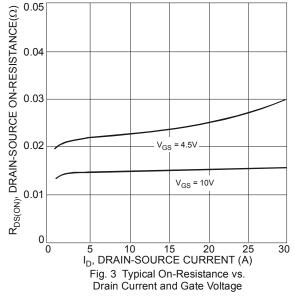
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	@T <sub>C</sub> = +25°C	I <sub>DSS</sub>	_	_	1.0	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage		I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage		V <sub>GS(th)</sub>	1	1.5	2.1	V	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		D	_	14	21	mΩ	$V_{GS} = 10V, I_D = 7A$
Static Diam-Source On-Nesistance		R <sub>DS(ON)</sub>	_	18	32	11152	$V_{GS} = 4.5V, I_D = 5.6A$
Forward Transfer Admittance		Y <sub>fs</sub>	_	8.5	_	S	$V_{DS} = 5V, I_{D} = 7A$
Diode Forward Voltage		V <sub>SD</sub>	_	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance		C <sub>iss</sub>	_	751	-	pF	
Output Capacitance		Coss	_	121	1	pF	$V_{DS} = 10V, V_{GS} = 0V,$ $f = 1.0MHz$
Reverse Transfer Capacitance		C <sub>rss</sub>	_	110	-	pF	1.0W112
Gate Resistance		$R_g$	-	1.5	_	Ω	$V_{DS} = 10V$ , $V_{GS} = 0V$ , $f = 1.0MHz$
Total Gate Charge (4.5V)		Qg	+	9	_	nC	
Total Gate Charge (10V)		Qg	-/	17.4	_	nC	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,
Gate-Source Charge		Q <sub>gs</sub>	1-1	2.2		nC	I <sub>D</sub> = 6A
Gate-Drain Charge		Q <sub>gd</sub>		3	_	nC	
Turn-On Delay Time		t <sub>D(on)</sub>	-	2.5	<i>//</i>	ns	
Turn-On Rise Time		tr	_	6.6		ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,
Turn-Off Delay Time		t <sub>D(off)</sub>		19.0	<b>N</b> –	ns	$R_G = 6\Omega$ , $R_L = 1.8\Omega$ , $I_D = 6.7A$
Turn-Off Fall Time		t <sub>f</sub>		6.3	_	ns	

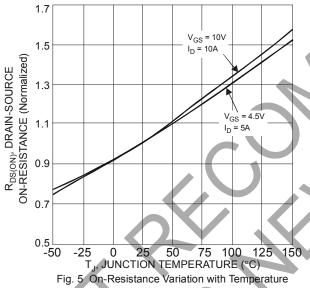
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing. Notes:











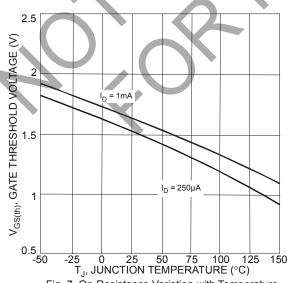
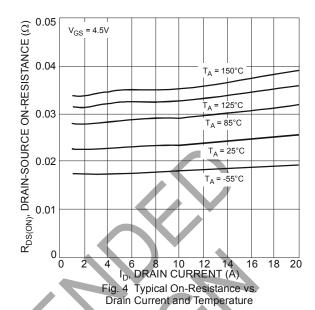
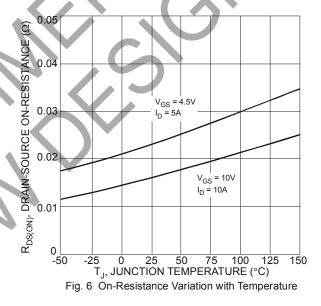


Fig. 7 On-Resistance Variation with Temperature





20 18 16 I<sub>S</sub>, SOURCE CURRENT (A) 12 10 T<sub>A</sub> = 25°C 2 0.4 0.5 0.6 0.7 0.8 0.9 V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V) Fig. 8 Diode Forward Voltage vs. Current



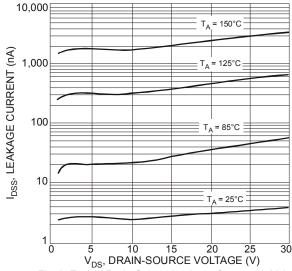
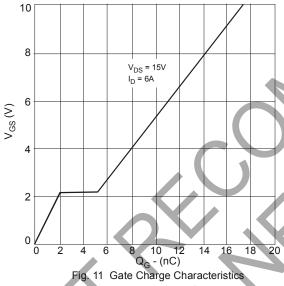
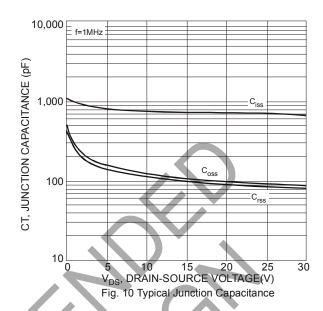
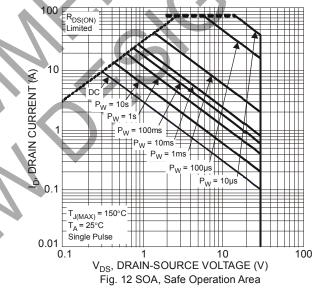


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage





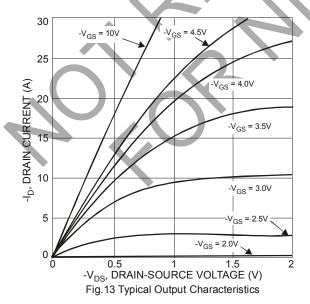


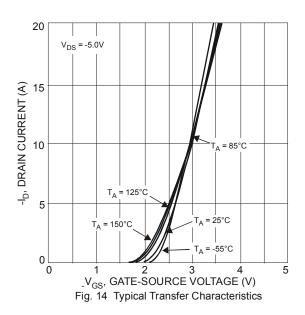


## Electrical Characteristics P-CHANNEL – Q2 (@T<sub>A</sub> = +25°C, unless otherwise specified.)

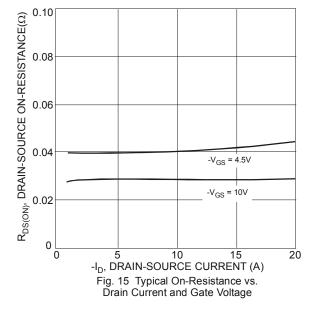
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V$ , $I_D = -250\mu A$
Zero Gate Voltage Drain Current	@T <sub>C</sub> = +25°C	I <sub>DSS</sub>		_	-1	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V
Gate-Source Leakage		I <sub>GSS</sub>		_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage		V <sub>GS(th)</sub>	-1	-1.7	-2.2	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance		D	1	30	39	mΩ	$V_{GS} = -10V$ , $I_D = -4.3A$
Static Dialii-Source Oil-Resistance		R <sub>DS</sub> (ON)	1	42	53	11152	$V_{GS} = -4.5V$ , $I_D = -3.7A$
Forward Transfer Admittance		Y <sub>fs</sub>	1	10	_	S	$V_{DS} = -5V$ , $I_D = -4.3A$
Diode Forward Voltage		$V_{SD}$	1	-0.75	-1.0	>	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance		C <sub>iss</sub>	_	1039	-	pF	
Output Capacitance		Coss		144	1	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz
Reverse Transfer Capacitance		C <sub>rss</sub>		134	1	pF	1.00112
Gate Resistance		$R_g$	_	13	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (4.5V)		Qg	+	10.1	_	nC	
Total Gate Charge (10V)		Qg	1	21.1	_	nC	$V_{GS} = -10V, V_{DS} = -15V,$
Gate-Source Charge		Q <sub>gs</sub>		2.8	Ţ	nC	I <sub>D</sub> = -6A
Gate-Drain Charge		Q <sub>gd</sub>		3.2		nC	
Turn-On Delay Time		t <sub>D(on)</sub>		10.1		ns	
Turn-On Rise Time		tr	<u> </u>	6.5		ns	$V_{DS} = -15V, V_{GS} = -10V,$
Turn-Off Delay Time		$t_{D(off)}$	_	50.1		ns	$R_G = 6\Omega$ , $I_D = -1A$
Turn-Off Fall Time		t <sub>f</sub>	I	22.2	<i></i>	ns	

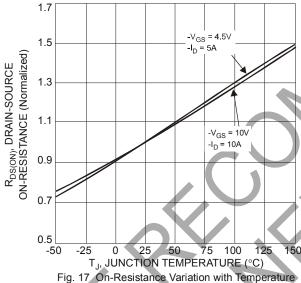
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing. Notes:

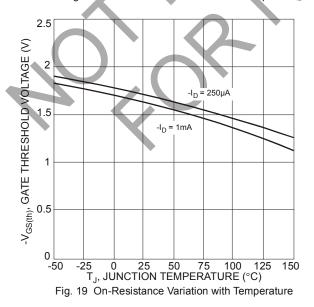


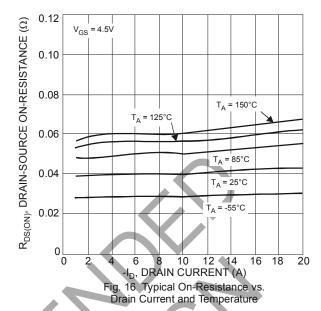


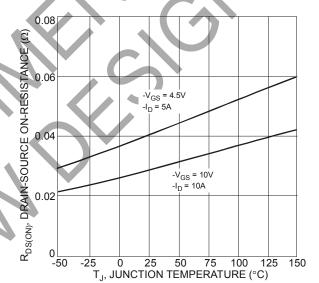


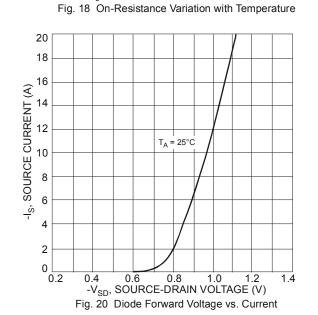




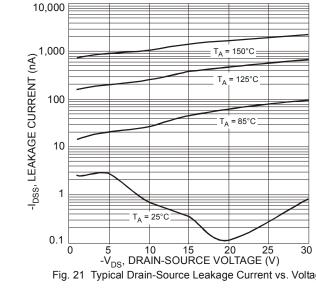


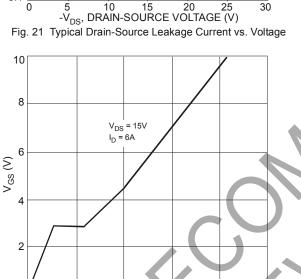




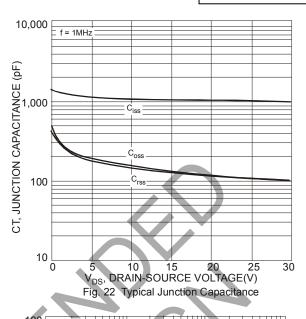


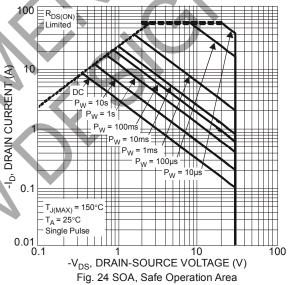






Q<sub>G</sub> - (nC)
Fig. 23 Gate Charge Characteristics





r(t), TRANSIENT THERMAL RESISTANC D = 0.5 D = 0.3 D = 0.9D = 0.1 0.01  $R_{\theta JA}(t) = r(t) * R_{\theta JA}$  $R_{\theta JA} = 46^{\circ}C/W$ Duty Cycle, D = t1 / t2 0.00001 0.0001 0.001 0.01 0.1 10 100 1,000 T1, PULSE DURATION TIME (sec) Fig. 25 Transient Thermal Resistance

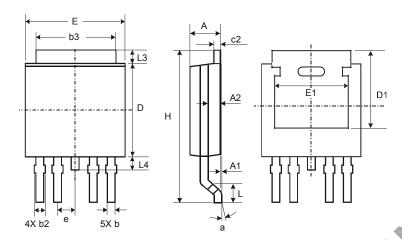
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### **Package Outline Dimensions**

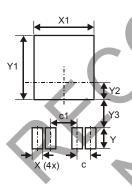
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TO252-4							
Dim	Min	Max	Тур				
Α	2.19	2.39	2.29				
A1	0.00	0.13	0.08				
A2	0.97	1.17	1.07				
b	0.51	0.71	0.583				
b2	0.61	0.79	0.70				
b3	5.21	5.46	5.33				
c2	0.45	0.58	0.531				
D	6.00	6.20	6.10				
D1	5.21		-				
е		_	1.27				
ш	6.45	6.70	6.58				
E1	4.32		_				
Н	9.40	10.41	9.91				
L	1.40	1.78	1.59				
L3	0.88	1.27	1.08				
L4	0.64	1.02	0.83				
а	0°	10°	_				
ΑII	Dimen	sions i	n mm				

### Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	1.27
c1	2.54
Х	1.00
X1	5.73
Y	2.00
Y1	6.17
Y2	1.64
Y3	2 66



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